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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	DMA, I²S, POR, PWM, WDT
Number of I/O	84
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 1x12b, 3x16b; D/A 3x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32f373v8t6

Do not reconfigure GPIO pins which are not present on 48 and 64 pin packages to the analog mode. Additional current consumption in the range of tens of µA per pin can be observed if V_{DDA} is higher than V_{DDIO}.

3.10 Direct memory access (DMA)

The flexible 12-channel, general-purpose DMA is able to manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers. The DMA controller supports circular buffer management, avoiding the generation of interrupts when the controller reaches the end of the buffer.

Each channel is connected to dedicated hardware DMA requests, with software trigger support for each channel. Configuration is done by software and transfer sizes between source and destination are independent.

The two DMAs can be used with the main peripherals: SPIs, I2Cs, USARTs, DACs, ADC, SDADCs, general-purpose timers.

3.11 Interrupts and events

3.11.1 Nested vectored interrupt controller (NVIC)

The STM32F373xx devices embed a nested vectored interrupt controller (NVIC) able to handle up to 60 maskable interrupt channels and 16 priority levels.

The NVIC benefits are the following:

- Closely coupled NVIC gives low latency interrupt processing
- Interrupt entry vector table address passed directly to the core
- Closely coupled NVIC core interface
- Allows early processing of interrupts
- Processing of late arriving higher priority interrupts
- Support for tail chaining
- Processor state automatically saved
- Interrupt entry restored on interrupt exit with no instruction overhead

The NVIC hardware block provides flexible interrupt management features with minimal interrupt latency.

3.11.2 Extended interrupt/event controller (EXTI)

The extended interrupt/event controller consists of 29 edge detector lines used to generate interrupt/event requests and wake-up the system. Each line can be independently configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The EXTI can detect an external line with a pulse width shorter than the internal clock period. Up to 84 GPIOs can be connected to the 16 external interrupt lines.

3.17.1 General-purpose timers (TIM2 to TIM5, TIM12 to TIM17, TIM19)

There are eleven synchronizable general-purpose timers embedded in the STM32F373xx (see *Table 5* for differences). Each general-purpose timer can be used to generate PWM outputs, or act as a simple time base.

- TIM2, 3, 4, 5 and 19

  These five timers are full-featured general-purpose timers:

  – TIM2 and TIM5 have 32-bit auto-reload up/downcounters and 32-bit prescalers

  – TIM3, 4, and 19 have 16-bit auto-reload up/downcounters and 16-bit prescalers

  These timers all feature 4 independent channels for input capture/output compare, PWM or one-pulse mode output. They can work together, or with the other general-purpose timers via the Timer Link feature for synchronization or event chaining.

  The counters can be frozen in debug mode.

  All have independent DMA request generation and support quadrature encoders.

- TIM12, 13, 14, 15, 16, 17

  These six timers general-purpose timers with mid-range features:

  They have 16-bit auto-reload upcounters and 16-bit prescalers.

  – TIM12 has 2 channels

  – TIM13 and TIM14 have 1 channel

  – TIM15 has 2 channels and 1 complementary channel

  – TIM16 and TIM17 have 1 channel and 1 complementary channel

  All channels can be used for input capture/output compare, PWM or one-pulse mode output.

  The timers can work together via the Timer Link feature for synchronization or event chaining. The timers have independent DMA request generation.

  The counters can be frozen in debug mode.

3.17.2 Basic timers (TIM6, TIM7, TIM18)

These timers are mainly used for DAC trigger generation. They can also be used as a generic 16-bit time base.

Table 10. Legend/abbreviations used in the pinout table

Name		Abbreviation	Definition
Pin name		Unless otherwise specified in brackets below the pin name, the pin function during and after reset is the same as the actual pin name	
Pin type		S	Supply pin
		I	Input only pin
		I/O	Input / output pin
I/O structure		FT	5 V tolerant I/O
		FTf	5 V tolerant I/O, FM+ capable
		TTa	3.3 V tolerant I/O directly connected to ADC
		TC	Standard 3.3 V I/O
		B	Dedicated BOOT0 pin
		RST	Bidirectional reset pin with embedded weak pull-up resistor
Notes		Unless otherwise specified by a note, all I/Os are set as floating inputs during and after reset	
Pin functions	Alternate functions	Functions selected through GPIOx_AFR registers	
	Additional functions	Functions directly selected/enabled through peripheral registers	

Table 11. STM32F373xx pin definitions

Pin numbers				Pin name (function after reset)	Pin type	I/O structure	Notes	Pin functions	
LQFP100	UFBGA100	LQFP64	LQFP48					Alternate function	Additional functions
1	B2	-	-	PE2	I/O	FT	(2)	TSC_G7_IO1, TRACECLK	-
2	A1	-	-	PE3	I/O	FT	(2)	TSC_G7_IO2, TRACED0	-
3	B1	-	-	PE4	I/O	FT	(2)	TSC_G7_IO3, TRACED1	-
4	C2	-	-	PE5	I/O	FT	(2)	TSC_G7_IO4, TRACED2	-
5	D2	-	-	PE6	I/O	FT	(2)	TRACED3	WKUP3, RTC_TAMPER3
6	E2	1	1	VBAT	S	-	-	Backup power supply	
7	C1	2	2	PC13(1)	I/O	TC	-	-	WKUP2, ALARM_OUT, CALIB_OUT, TIMESTAMP, RTC_TAMPER1

Table 11. STM32F373xx pin definitions (continued)

Pin numbers				Pin name (function after reset)	Pin type	I/O structure	Notes	Pin functions	
LQFP100	UFBGA100	LQFP64	LQFP48					Alternate function	Additional functions
51	L12	-	-	VDDSD3	S	-	(2)	SDADC3 power supply	
52	K12	33	25	VREFSD+	S	-	-	External reference voltage for SDADC1, SDADC2, SDADC3 (positive input)	
53	K11	34	26	PB14	I/O	TC	(4)	SPI2_MISO/I2S2_MCK, USART3_RTS, TIM15_CH1, TIM12_CH1, TSC_G6_IO1	SDADC3_AIN8P
54	K10	35	27	PB15	I/O	TC	(4)	SPI2_MOSI/I2S2_SD, TIM15_CH1N, TIM15_CH2, TIM12_CH2, TSC_G6_IO2, RTC_REFIN	SDADC3_AIN7P, SDADC3_AIN8M
55	K9	36	28	PD8	I/O	TC	(4)	SPI2_SCK/I2S2_CK, USART3_TX, TSC_G6_IO3	SDADC3_AIN6P
56	K8	-	-	PD9	I/O	TC	(4) (2)	USART3_RX, TSC_G6_IO4	SDADC3_AIN5P, SDADC3_AIN6M
57	J12	-	-	PD10	I/O	TC	(4) (2)	USART3_CK	SDADC3_AIN4P
58	J11	-	-	PD11	I/O	TC	(4) (2)	USART3_CTS	SDADC3_AIN3P, SDADC3_AIN4M
59	J10	-	-	PD12	I/O	TC	(4) (2)	USART3_RTS, TIM4_CH1, TSC_G8_IO1	SDADC3_AIN2P
60	H12	-	-	PD13	I/O	TC	(4) (2)	TIM4_CH2, TSC_G8_IO2	SDADC3_AIN1P, SDADC3_AIN2M
61	H11	-	-	PD14	I/O	TC	(4) (2)	TIM4_CH3, TSC_G8_IO3	SDADC3_AIN0P
62	H10	-	-	PD15	I/O	TC	(4) (2)	TIM4_CH4, TSC_G8_IO4	SDADC3_AIN0M
63	E12	37	-	PC6	I/O	FT	(2)	TIM3_CH1, SPI1_NSS/I2S1_WS	-
64	E11	38	-	PC7	I/O	FT	(2)	TIM3_CH2, SPI1_SCK/I2S1_CK,	-
65	E10	39	-	PC8	I/O	FT	(2)	SPI1_MISO/I2S1_MCK, TIM3_CH3	-
66	D12	40	-	PC9	I/O	FT	(2)	SPI1_MOSI/I2S1_SD, TIM3_CH4	-

Table 11. STM32F373xx pin definitions (continued)

Pin numbers				Pin name (function after reset)	Pin type	I/O structure	Notes	Pin functions	
LQFP100	UFBGA100	LQFP64	LQFP48					Alternate function	Additional functions
67	D11	41	29	PA8	I/O	FT	-	SPI2_SCK/I2S2_CK, I2C2_SMBA, USART1_CK, TIM4_ETR, TIM5_CH1_ETR, MCO	-
68	D10	42	30	PA9	I/O	FTf	-	SPI2_MISO/I2S2_MCK, I2C2_SCL, USART1_TX, TIM2_CH3, TIM15_BKIN, TIM13_CH1, TSC_G4_IO1	-
69	C12	43	31	PA10	I/O	FTf	-	SPI2_MOSI/I2S2_SD, I2C2_SDA, USART1_RX, TIM2_CH4, TIM17_BKIN, TIM14_CH1, TSC_G4_IO2	-
70	B12	44	32	PA11	I/O	FT	-	SPI2_NSS/I2S2_WS, SPI1_NSS/I2S1_WS, USART1_CTS, CAN_RX, TIM4_CH1, USB_DM, TIM5_CH2, COMP1_OUT	-
71	A12	45	33	PA12	I/O	FT	-	SPI1_SCK/I2S1_CK, USART1_RTS, CAN_TX, USB_DP, TIM16_CH1, TIM4_CH2, TIM5_CH3, COMP2_OUT	-
72	A11	46	34	PA13	I/O	FT	-	SPI1_MISO/I2S1_MCK, USART3_CTS, IR_OUT, TIM16_CH1N, TIM4_CH3, TIM5_CH4, TSC_G4_IO3, SWDIO-JTMS	-
73	C11	47	35	PF6	I/O	FTf	-	SPI1_MOSI/I2S1_SD, USART3_RTS, TIM4_CH4, I2C2_SCL	-
74	F11	-	-	VSS_3	S	-	(2)	Ground	
75	G11	-	-	VDD_3	S	-	(2)	Digital power supply	
-	-	48	36	PF7	I/O	FTf	-	I2C2_SDA, USART2_CK	-
76	A10	49	37	PA14	I/O	FTf	-	I2C1_SDA, TIM12_CH1, TSC_G4_IO4, SWCLK-JTCK	-

Table 12. Alternate functions for port PA

Pin Name	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF14	AF15
PA0	-	TIM2_CH1_ETR	TIM5_CH1_ETR	TSC_G1_IO1	-	-	-	USART2_CTS	COMP1_OUT	-	-	TIM19_CH1	-	EVENTOUT
PA1	RTC_REFIN	TIM2_CH2	TIM5_CH2	TSC_G1_IO2	-	-	SPI3_SCK/I2S3_CK	USART2_RTS	-	TIM15_CH1N	-	TIM19_CH2	-	EVENTOUT
PA2	-	TIM2_CH3	TIM5_CH3	TSC_G1_IO3	-	-	SPI3_MISO/I2S3_MCK	USART2_TX	COMP2_OUT	TIM15_CH1	-	TIM19_CH3	-	EVENTOUT
PA3	-	TIM2_CH4	TIM5_CH4	TSC_G1_IO4	-	-	SPI3_MOSI/I2S3_SD	USART2_RX	-	TIM15_CH2	-	TIM19_CH4	-	EVENTOUT
PA4	-	-	TIM3_CH2	TSC_G2_IO1	-	SPI1_NSS/I2S1_WS	SPI3_NSS/I2S3_WS	USART2_CK	-	-	TIM12_CH1	-	-	EVENTOUT
PA5	-	TIM2_CH1_ETR	-	TSC_G2_IO2	-	SPI1_SCK/I2S1_CK	-	CEC	-	TIM14_CH1	TIM12_CH2	-	-	EVENTOUT
PA6	-	TIM16_CH1	TIM3_CH1	TSC_G2_IO3	-	SPI1_MISO/I2S1_MCK	-	-	COMP1_OUT	TIM13_CH1	-	-	-	EVENTOUT
PA7	-	TIM17_CH1	TIM3_CH2	TSC_G2_IO4	-	SPI1_MOSI/I2S1_SD	-	-	COMP2_OUT	TIM14_CH1	-	-	-	EVENTOUT
PA8	MCO	-	TIM5_CH1_ETR	-	I2C2_SMBA	SPI2_SCK/I2S2_CK	-	USART1_CK	-	-	TIM4_ETR	-	-	EVENTOUT
PA9	-	-	TIM13_CH1	TSC_G4_IO1	I2C2_SCL	SPI2_MISO/I2S2_MCK	-	USART1_TX	-	TIM15_BKIN	TIM2_CH3	-	-	EVENTOUT
PA10	-	TIM17_BKIN	-	TSC_G4_IO2	I2C2_SDA	SPI2_MOSI/I2S2_SD	-	USART1_RX	-	TIM14_CH1	TIM2_CH4	-	-	EVENTOUT
PA11	-	-	TIM5_CH2	-	-	SPI2_NSS/I2S2_WS	SPI1_NSS/I2S1_WS	USART1_CTS	COMP1_OUT	CAN_RX	TIM4_CH1	-	-	EVENTOUT
PA12	-	TIM16_CH1	TIM5_CH3	-	-	-	SPI1_SCK/I2S1_CK	USART1_RTS	COMP2_OUT	CAN_TX	TIM4_CH2	-	-	EVENTOUT

6 Electrical characteristics

6.1 Parameter conditions

Unless otherwise specified, all voltages are referenced to V_{SS}.

6.1.1 Minimum and maximum values

Unless otherwise specified, the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at T_A = 25 °C and T_A = $T_A$max (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean±3σ).

6.1.2 Typical values

Unless otherwise specified, typical data are based on T_A = 25 °C, V_{DD} = V_{DDA} = V_{DDSDx} = 3.3 V. They are given only as design guidelines and are not tested.

Typical ADC and SDADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95% of the devices have an error less than or equal to the value indicated (mean±2σ).

6.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

6.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in *Figure 7*.

6.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in *Figure 8*.

Figure 7. Pin loading conditions

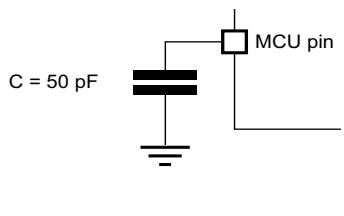
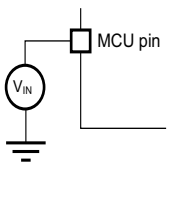
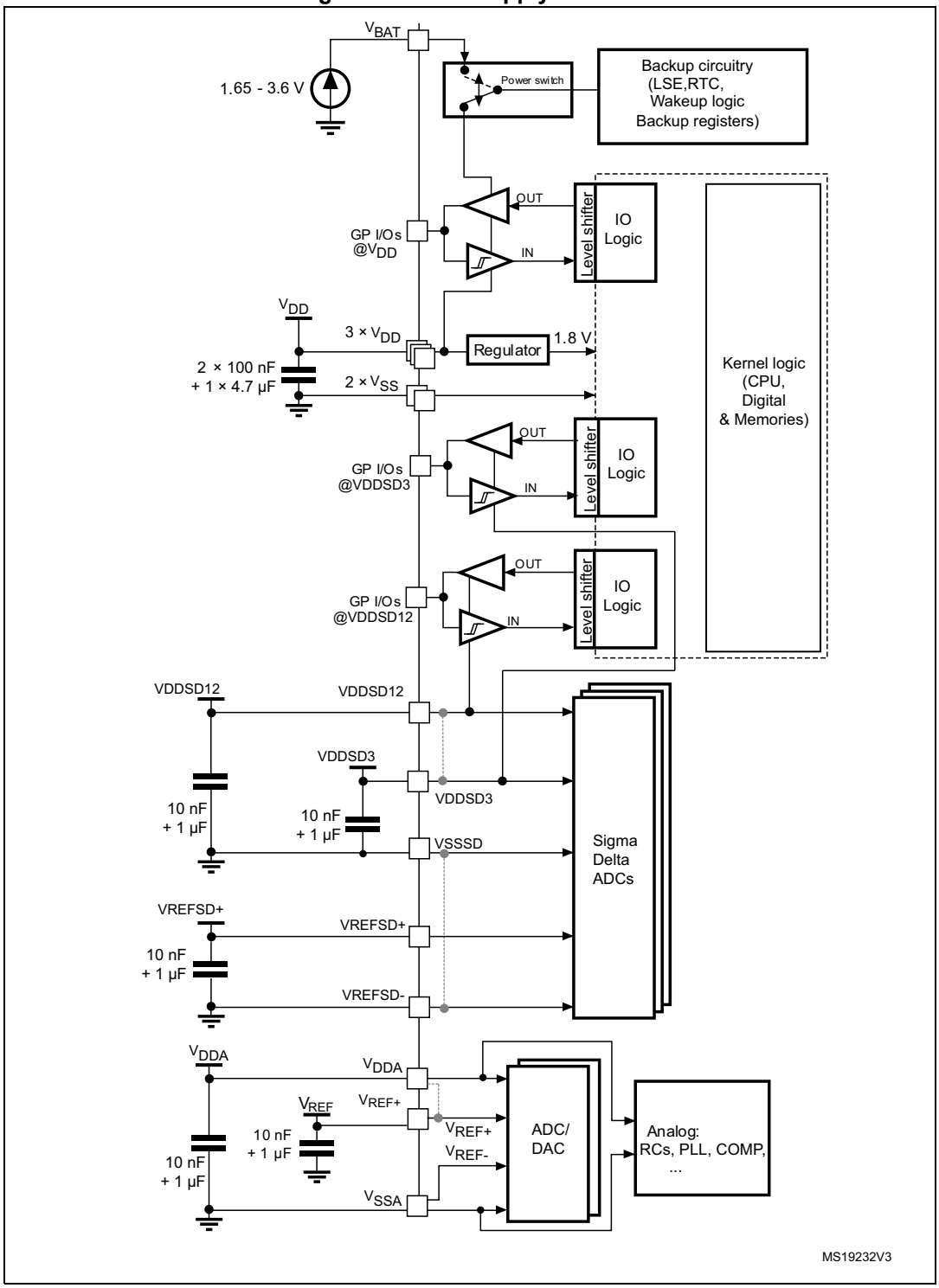


Figure 8. Pin input voltage



6.1.6 Power supply scheme

Figure 9. Power supply scheme



1. Dotted lines represent the internal connections on low pin count packages, joining the dedicated supply pins.

Table 36. Peripheral current consumption (continued)

Peripheral	Typical consumption[1]	Unit
APB1 peripherals		µA/MHz
APB1-Bridge[3]	6.9	
TIM2	47.9	
TIM3	36.8	
TIM4	36.9	
TIM5	45.5	
TIM6	8.4	
TIM7	8.2	
TIM12	21.3	
TIM13	14.2	
TIM14	14.4	
TIM18	10.1	
WWDG	4.7	
SPI2	24.3	
SPI3	25.3	
USART2	45.3	
USART3	43.1	
I2C1	14.0	
I2C2	13.9	
USB	27.9	
CAN	38.1	
DAC2	7.7	
PWR	5.4	
DAC1	14.8	
CEC	5.4	

1. When peripherals are enabled, power consumption of the analog part of peripherals such as ADC, DACs, Comparators, etc. is not included. Refer to those peripherals characteristics in the subsequent sections.
2. The BusMatrix is automatically active when at least one master is ON (CPU, DMA1 or DMA2).
3. The APBx Bridge is automatically active when at least one peripheral is ON on the same Bus.

6.3.6 Wakeup time from low-power mode

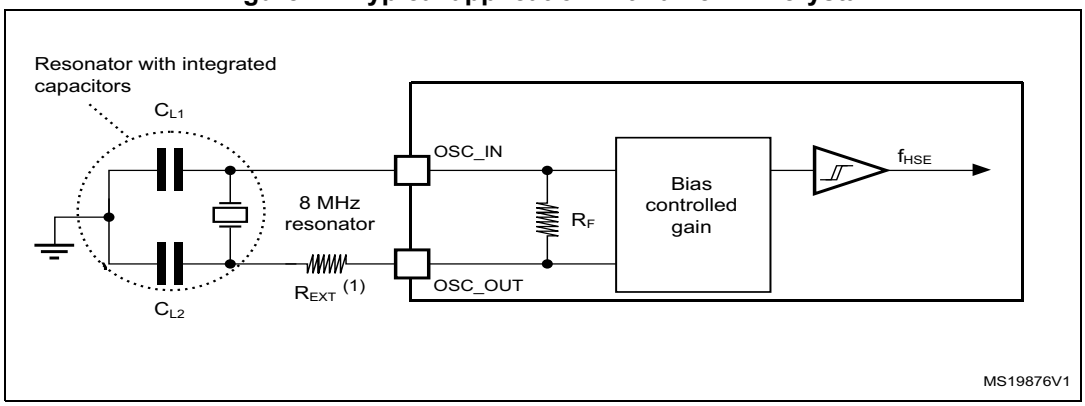
The wakeup times given in *Table 37* are measured from the wakeup event trigger to the first instruction executed by the CPU. The clock source used to wake up the device depends from the current operating mode:

- Stop or sleep mode: the wakeup event is WFE.
- The WKUP1 (PA0) pin is used to wakeup from standby, stop and sleep modes.

For C_{L1} and C_{L2}, it is recommended to use high-quality external ceramic capacitors in the 5 pF to 20 pF range (typ.), designed for high-frequency applications, and selected to match the requirements of the crystal or resonator (see *Figure 14*). C_{L1} and C_{L2} are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of C_{L1} and C_{L2}. PCB and MCU pin capacitance must be included (10 pF can be used as a rough estimate of the combined pin and board capacitance) when sizing C_{L1} and C_{L2}.

Note: For information on electing the crystal, refer to the application note AN2867 "Oscillator design guide for ST microcontrollers" available from the ST website www.st.com.

Figure 14. Typical application with an 8 MHz crystal



1. R_{EXT} value depends on the crystal characteristics.

6.3.17 12-bit ADC characteristics

Unless otherwise specified, the parameters given in *Table 60* are preliminary values derived from tests performed under ambient temperature, f_{PCLK2} frequency and V_{DDA} supply voltage conditions summarized in *Table 22*.

Note: It is recommended to perform a calibration after each power-up.

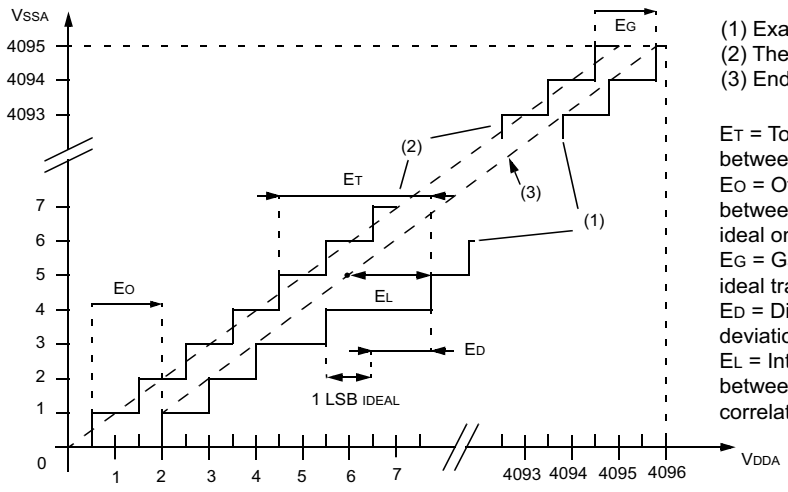
Table 60. ADC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Power supply	-	2.4	-	3.6	V
V_{REF+}	Positive reference voltage	-	2.4	-	V_{DDA}	V
V_{REF-}	Negative reference voltage	-	0	-	-	V
$I_{DDA(ADC)}$(1)	Current consumption from V_{DDA}	$V_{DD} = V_{DDA} = 3.3$ V	-	0.9	-	mA
I_{VREF}	Current on the V_{REF} input pin	-	-	160(2)	220(2)	µA
f_{ADC}	ADC clock frequency	-	0.6	-	14	MHz
f_S(3)	Sampling rate	-	0.05	-	1	MHz
f_{TRIG}(3)	External trigger frequency	f_{ADC} = 14 MHz	-	-	823	kHz
		-	-	-	17	$1/f_{ADC}$
V_{AIN}	Conversion voltage range	-	0 (V_{SSA} or V_{REF-} tied to ground)	-	V_{REF+}	V
R_{SRC}(3)	Signal source impedance	See *Equation 1* and *Table 61* for details	-	-	50	kΩ
R_{ADC}(3)	Sampling switch resistance	-	-	-	1	kΩ
C_{ADC}(3)	Internal sample and hold capacitor	-	-	-	8	pF
t_{CAL}(3)	Calibration time	f_{ADC} = 14 MHz	5.9			µs
		-	83			$1/f_{ADC}$
t_{lat}(3)	Injection trigger conversion latency	f_{ADC} = 14 MHz	-	-	0.214	µs
		-	-	-	2(4)	$1/f_{ADC}$
t_{latr}(3)	Regular trigger conversion latency	f_{ADC} = 14 MHz	-	-	0.143	µs
		-	-	-	2(4)	$1/f_{ADC}$
t_S(3)	Sampling time	f_{ADC} = 14 MHz	0.107	-	17.1	µs
		-	1.5	-	239.5	$1/f_{ADC}$
t_{STAB}(3)	Power-up time	-	-	-	1	µs
t_{CONV}(3)	Total conversion time (including sampling time)	f_{ADC} = 14 MHz	1	-	18	µs
		-	14 to 252 (t_S for sampling +12.5 for successive approximation)			$1/f_{ADC}$

1. During conversion of the sampled value (12.5 x ADC clock period), an additional consumption of 100 µA on I_{DDA} and 60 µA on I_{DD} is present
2. Guaranteed by characterization results.
3. Guaranteed by design.
4. For external triggers, a delay of $1/f_{PCLK2}$ must be added to the latency specified in *Table 60*

2. ADC accuracy vs. negative injection current: Injecting a negative current on any analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative currents.
   Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\Sigma I_{INJ(PIN)}$ in *Section 6.3.14* does not affect the ADC accuracy.
3. Better performance may be achieved in restricted V_{DDA}, frequency and temperature ranges.
4. Guaranteed by characterization results.

Figure 27. ADC accuracy characteristics

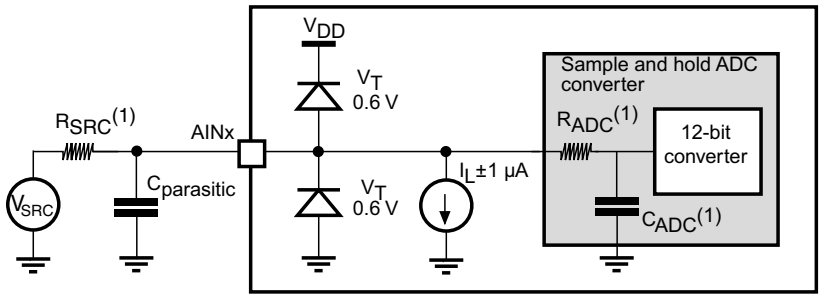


(1) Example of an actual transfer curve
(2) The ideal transfer curve
(3) End point correlation line

E_T = Total Unajusted Error: maximum deviation between the actual and ideal transfer curves.
E_O = Offset Error: maximum deviation between the first actual transition and the first ideal one.
E_G = Gain Error: deviation between the last ideal transition and the last actual one.
E_D = Differential Linearity Error: maximum deviation between actual steps and the ideal ones.
E_L = Integral Linearity Error: maximum deviation between any actual transition and the end point correlation line.

MS19880V2

Figure 28. Typical connection diagram using the ADC



MS32163V1

1. Refer to *Table 60* for the values of R_{SRC}, R_{ADC} and C_{ADC}.
2. $C_{parasitic}$ represents the capacitance of the PCB (dependent on soldering and PCB layout quality) plus the pad capacitance (roughly 7 pF). A high $C_{parasitic}$ value will downgrade conversion accuracy. To remedy this, f_{ADC} should be reduced.

General PCB design guidelines

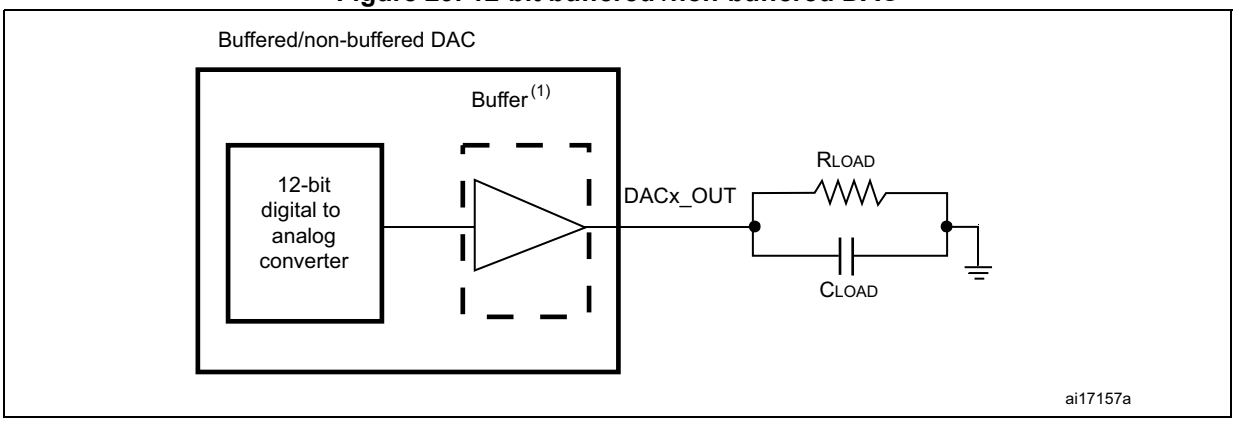
Power supply decoupling should be performed as shown in *Figure 9*. The 10 nF capacitor should be ceramic (good quality) and it should be placed as close as possible to the chip.

Table 63. DAC characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Offset(3)	Offset error (difference between measured value at Code (0x800) and the ideal value = V_{REF+}/2)	-	-	-	±10	mV
		Given for the DAC in 10-bit at V_{REF+} = 3.6 V	-	-	±3	LSB
		Given for the DAC in 12-bit at V_{REF+} = 3.6 V	-	-	±12	LSB
Gain error(3)	Gain error	Given for the DAC in 12bit configuration	-	-	±0.5	%
$t_{SETTLING}$(3)	Settling time (full scale: for a 10-bit input code transition between the lowest and the highest input codes when DAC_OUT reaches final value ±1LSB	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ kΩ	-	3	4	µs
Update rate(3)	Max frequency for a correct DAC_OUT change when small variation in the input code (from code i to i+1LSB)	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ kΩ	-	-	1	MS/s
t_{WAKEUP}(3)	Wakeup time from off state (Setting the ENx bit in the DAC Control register)	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ kΩ input code between lowest and highest possible ones.	-	6.5	10	µs
PSRR+ (1)	Power supply rejection ratio (to V_{DDA}) (static DC measurement	No R_{LOAD}, C_{LOAD} = 50 pF	-	-67	-40	dB

1. Guaranteed by design.
2. Quiescent mode refers to the state of the DAC keeping a steady value on the output, so no dynamic consumption is involved.
3. Guaranteed by characterization.

Figure 29. 12-bit buffered /non-buffered DAC



1. The DAC integrates an output buffer that can be used to reduce the output impedance and to drive external loads directly without the use of an external operational amplifier. The buffer can be bypassed by configuring the BOFFx bit in the DAC_CR register.

6.3.19 Comparator characteristics

Table 64. Comparator characteristics

Symbol	Parameter	Conditions		Min	Typ	Max(1)	Unit
V_{DDA}	Analog supply voltage	-		2	-	3.6	V
V_{IN}	Comparator input voltage range	-		0	-	V_{DDA}	V
V_{BG}	V_{REFINT} scaler input voltage	-		-	1.2	-	V
V_{SC}	V_{REFINT} scaler offset voltage	-		-	±5	±10	mV
t_{S_SC}	Scaler startup time from power down	First V_{REFINT} scaler activation after device power on		-	-	1000(2)	ms
		Next activations				0.2	
t_{START}	Comparator startup time	Startup time to reach propagation delay specification		-	-	60	µs
t_D	Propagation delay for 200 mV step with 100 mV overdrive	Ultra-low power mode		-	2	4.5	µs
		Low power mode		-	0.7	1.5	
		Medium power mode		-	0.3	0.6	
		High speed mode	$V_{DDA} \geq 2.7$ V	-	50	100	ns
			$V_{DDA} < 2.7$ V	-	100	240	
	Propagation delay for full range step with 100 mV overdrive	Ultra-low power mode		-	2	7	µs
		Low power mode		-	0.7	2.1	
		Medium power mode		-	0.3	1.2	
		High speed mode	$V_{DDA} \geq 2.7$ V	-	90	180	ns
			$V_{DDA} < 2.7$ V	-	110	300	
V_{offset}	Comparator offset error	-		-	±4	±10	mV
dV_{offset}/dT	Offset error temperature coefficient	-		-	18	-	µV/°C
$I_{DD(COMP)}$	COMP current consumption	Ultra-low power mode		-	1.2	1.5	µA
		Low power mode		-	3	5	
		Medium power mode		-	10	15	
		High speed mode		-	75	100	

1. Guaranteed by characterization results.
2. Integral linearity error can be improved by software calibration of SDADC transfer curve (2-nd order polynomial calibration).
3. For f_{ADC} lower than 5 MHz, there will be a performance degradation of around 2 dB due to flicker noise increase.
4. If the reference value is lower than 2.4 V, there will be a performance degradation proportional to the reference supply drop, according to this formula: $20*\log10(V_{REF}/2.4)$ dB
5. SNR, THD, SINAD parameters are valid for frequency bandwidth 20Hz - 1kHz. Input signal frequency is 300Hz (for f_{ADC}=6MHz) and 100Hz (for f_{ADC}=1.5MHz).

Table 75. VREFSD+ pin characteristics(1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	Note
V_{REFINT}	Internal reference voltage	Buffered embedded reference voltage (1.2 V)	-	1.2	-	V	See *Section 6.3.4: Embedded reference voltage on page 60*
		Embedded reference voltage amplified by factor 1.5	-	1.8	-	V	-
$C_{VREFSD+}$(2)	Reference voltage filtering capacitor	$V_{REFSD+} = V_{REFINT}$	1000	-	10000	nF	-
$R_{VREFSD+}$	Reference voltage input impedance	Normal mode (f_{ADC} = 6 MHz)	-	238	-	kΩ	See RM0313 reference manual for detailed description
		Slow mode (f_{ADC} = 1.5 MHz)	-	952	-		

1. Guaranteed by characterization results.
2. If internal reference voltage is selected then this capacitor is charged through internal resistance - typ. 300 ohm. If internal reference source is selected through the reference voltage selection bits (REFV<>”00” in SDADC_CR1 register), the application must first configure REFV bits and then wait for capacitor charging. Recommended waiting time is 3 ms if 1 µF capacitor is used.

Table 76. UFBGA100 - 100-pin, 7 x 7 mm, 0.50 mm pitch, ultra fine pitch ball grid array package mechanical data (continued)

Symbol	millimeters			inches[1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D	6.950	7.000	7.050	0.2736	0.2756	0.2776
D1	5.450	5.500	5.550	0.2146	0.2165	0.2185
E	6.950	7.000	7.050	0.2736	0.2756	0.2776
E1	5.450	5.500	5.550	0.2146	0.2165	0.2185
e	-	0.500	-	-	0.0197	-
F	0.700	0.750	0.800	0.0276	0.0295	0.0315
ddd	-	-	0.100	-	-	0.0039
eee	-	-	0.150	-	-	0.0059
fff	-	-	0.050	-	-	0.0020

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 33. UFBGA100 - 100-pin, 7 x 7 mm, 0.50 mm pitch, ultra fine pitch ball grid array package recommended footprint

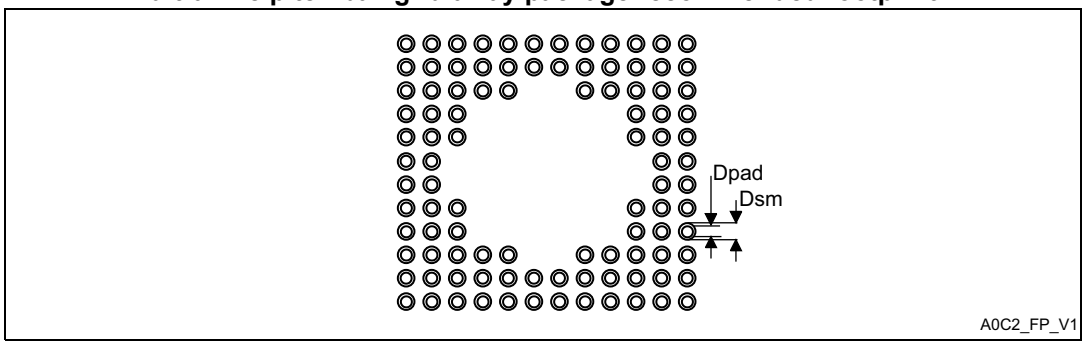


Table 77. UFBGA100 recommended PCB design rules (0.5 mm pitch BGA)

Dimension	Recommended values
Pitch	0.5
Dpad	0.280 mm
Dsm	0.370 mm typ. (depends on the soldermask registration tolerance)
Stencil opening	0.280 mm
Stencil thickness	Between 0.100 mm and 0.125 mm

Table 80. LQFP48 - 48-pin, 7 x 7 mm low-profile quad flat package mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	8.800	9.000	9.200	0.3465	0.3543	0.3622
D1	6.800	7.000	7.200	0.2677	0.2756	0.2835
D3	-	5.500	-	-	0.2165	-
E	8.800	9.000	9.200	0.3465	0.3543	0.3622
E1	6.800	7.000	7.200	0.2677	0.2756	0.2835
E3	-	5.500	-	-	0.2165	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7°	0°	3.5°	7°
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

7.5 Thermal characteristics

The maximum chip junction temperature ($T_J$max) must never exceed the values given in *Table 22: General operating conditions*.

The maximum chip-junction temperature, T_J max, in degrees Celsius, may be calculated using the following equation:

T_J max = T_A max + (P_D max x Q_{JA})

Where:

- T_A max is the maximum ambient temperature in °C,
- Q_{JA} is the package junction-to-ambient thermal resistance, in °C/W,
- P_D max is the sum of P_{INT} max and $P_{I/O}$ max (P_D max = P_{INT} max + $P_{I/O}$max),
- P_{INT} max is the product of I_{DD} and V_{DD}, expressed in Watts. This is the maximum chip internal power.

$P_{I/O}$ max represents the maximum power dissipation on output pins where:

$P_{I/O}$ max = S (V_{OL} × I_{OL}) + S((V_{DD} – V_{OH}) × I_{OH}),

taking into account the actual V_{OL} / I_{OL} and V_{OH} / I_{OH} of the I/Os at low and high level in the application.

Table 81. Package thermal characteristics

Symbol	Parameter	Value	Unit
Θ_{JA}	**Thermal resistance junction-ambient** LQFP64 - 10 × 10 mm / 0.5 mm pitch	45	°C/W
	Thermal resistance junction-ambient LQFP48 - 7 × 7 mm	55	
	Thermal resistance junction-ambient LQFP100 - 14 × 14 mm / 0.5 mm pitch	46	
	Thermal resistance junction-ambient UFBGA100 - 7 x 7 mm	59	

7.5.1 Reference document

JESD51-2 Integrated Circuits Thermal Test Method Environment Conditions - Natural Convection (Still Air). Available from www.jedec.org

Table 83. Document revision history (continued)

Date	Revision	Changes
19-Sep-2013	4	Replaced “Cortex-M4F” with “Cortex-M4” throughout the document. Removed part number STM32F372xx. Added “1.25 DMIPS/MHz (Dhrystone 2.1)” in *Features*. Updated *Introduction*. Added reference to the STMTouch touch sensing firmware library in *Section 3.16: Touch sensing controller (TSC)*. Added “All I2S interfaces can operate in half-duplex mode only.” in *Section 3.21: Serial peripheral interface (SPI)/Inter-integrated sound interfaces (I2S)*. Added row “I2S full-duplex mode” to *Table 9: STM32F373xx SPI/I2S implementation*. Modified introduction of *I2C interface characteristics*. Added alternate function RTC_REFIN and removed additional function RTC_REF_CLK_IN to pins PA1 and PB15. Replaced alternate function JNTRST with NJTRST for pin PB4. In *Table 12: Alternate functions for port PA*: replaced alternate function JTMS-SWDIO with SWDIO-JTMS for pin PA13, and JTCK-SWCLK with SWCLK-JTCK for pin PA14. Added rows V_{REF+} and V_{REFSD+} to *Table 22: General operating conditions*. Replaced "$f_{APB1} = f_{AHB/2}$" with "$f_{APB1} = f_{AHB}$" for “When the peripherals are enabled...” in *Typical current consumption*. Added COMP in *Table 36: Peripheral current consumption* Added conditions for f_{HSE_ext} in *Table 38: High-speed external user clock characteristics*. Added Min and Max values for ACC_{HSI} in *Table 42: HSI oscillator characteristics*. Replaced reference "JESD22-C101" with "ANSI/ESD STM5.3.1" in *Table 49: ESD absolute maximum ratings*. Removed pins PB0 and PB1 in description of I_{INJ} in *Table 51: I/O current injection susceptibility*. Updated *Table 56: I2C characteristics*. Replaced all occurrences of “gain/2” with “gain*2” in *Table 74: SDADC characteristics*. Corrected typo in *Figure 19: I/O AC characteristics definition*. Replaced *Figure 21: I2C bus AC waveforms and measurement circuit*.. Added $I_{DDA(ADC)}$ and footnote 1 in *Table 60: ADC characteristics*